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AUG 15 2005

In re the Application of

Applicant Xiaowei Deng, et al. Docket Number: TI-33969

Serial No.: 10/618,473 Art Unit: 2824

Filed: 07/11/03 Examiner: Van Thu T. Nguyen

For: System for Reducing Row Periphery Power Consumption
in Memory Devices

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NAME OF INVENTOR(S):	
Xiaowei Deng, et al.	
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